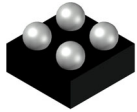
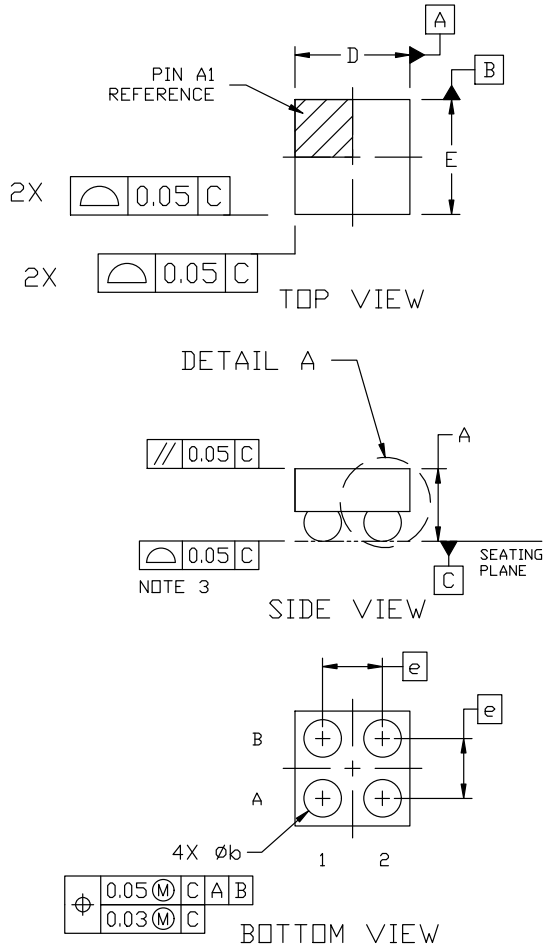


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



## WLCSP4 0.96x0.96x0.609 CASE 567FG ISSUE A

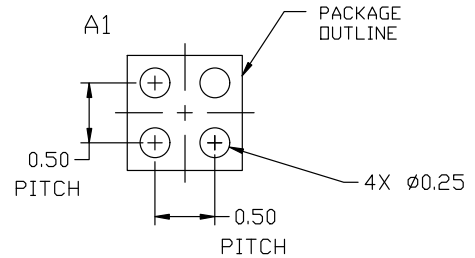
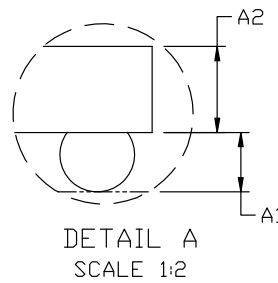
DATE 01 JUL 2022



NOTES:

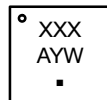
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.554	0.609	0.664
A1	0.219	0.249	0.279
A2	0.335	0.360	0.385
b	0.282	0.312	0.342
D	0.96 BSC		
E	0.96 BSC		
e	0.50 BSC		



\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAM\*



- XXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP4 0.96x0.96x0.609</b>	<b>PAGE 1 OF 1</b>

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